

Title (en)

FIXING DEVICE AND IMAGE FORMING APPARATUS INCORPORATING SAME

Title (de)

FIXIERVORRICHTUNG UND BILDERZEUGUNGSVORRICHTUNG DAMIT

Title (fr)

DISPOSITIF DE FIXATION ET APPAREIL DE FORMATION D'IMAGES LE COMPRENANT

Publication

**EP 3667430 A1 20200617 (EN)**

Application

**EP 19210703 A 20191121**

Priority

JP 2018221277 A 20181127

Abstract (en)

A fixing device (5) comprising a cylindrical fixing member (21), an opposed member (22) disposed opposite an outer surface of the fixing member (21), a nip formation pad (24) disposed inside a loop of the fixing member (21) to sandwich the fixing member (21) with the opposed member (22) to form a nip between the fixing member (21) with the opposed member (22), a heater (23) disposed inside the loop of the fixing member (21) to heat the nip formation pad (24), a reflector (25) which includes a part of a surface facing the heater (23) and having a lower reflectance than the another part of the surface of the reflector (25), wherein at least a part of the reflector (25) is disposed between the fixing member (21) and the heater (23) in a cross-section that intersects the width direction of the fixing member (21) and corresponding image forming apparatus.

IPC 8 full level

**G03G 15/20** (2006.01)

CPC (source: EP)

**G03G 15/2053** (2013.01); **G03G 2215/2035** (2013.01)

Citation (applicant)

JP 2016145852 A 20160812 - BROTHER IND LTD

Citation (search report)

- [XI] US 2014079455 A1 20140320 - SEKI TAKAYUKI [JP], et al
- [A] US 2016231673 A1 20160811 - ISHIDA KEI [JP]
- [A] US 2011188908 A1 20110804 - ISHIDA KEI [JP], et al
- [A] US 2014016971 A1 20140116 - ARAI YUJI [JP], et al
- [A] US 2013209147 A1 20130815 - OGAWA TADASHI [JP], et al

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**EP 3667430 A1 20200617; EP 3667430 B1 20230816;** JP 2020086160 A 20200604

DOCDB simple family (application)

**EP 19210703 A 20191121;** JP 2018221277 A 20181127